

Caractéristiques:

Article: BEST-509 80g pâte à braser

BEST-soudure (étain) pâte est le meilleur choix de reballing IC .original ,Qualité vérifiée

Plage d'utilisation: ordinateur portable / ordinateur / téléphone portable / appareils ménagers Réparations CMS et BGA IC, outils pour la réparation au niveau des puces

spécification

Joint de soudure blanc et dodu, aucun faux soudage, adhésif fort avec pointe de fer à souder. Indispensable outil pour la réparation d'équipement précis et ligne de fabrication électronique.

PRODUCT DISPLAY



PRODUCT DETAILS



Name: Tin Paste

Model: BST-509

Size: $\phi 36 \times 35$ mm

Weight: 80g

Composition: Sn63/Pb37

Melting point: 183°C



Storage: Chilled in refrigerator, the best refrigeration temperature is 5°C~10°C.

Features: 1. New technical support, unique chemical formula provides excellent wettability, ensuring high reliability.

2. Use highly effective thixotropic agents to effectively prevent the collapse of printing and preheating, and ensure good printing and fine pattern.

3. More advanced thermal insulation technology, adhesive durability, not easy to dry, sticky time up to 48 hours.

4. High quality, unique formulation, perfect performance, easy to weld, bright and full of welding spot, no such phenomenon as false welding or false welding.

5. The residue is colorless and transparent. It does not affect the monitoring, cleaning and cleaning performance.

6. Good moisturizing and dry resistance. Under normal temperature, the shelf life is longer, which is suitable for mobile phone maintenance, computer digital maintenance industry, high precision circuit board SMT welding, BGA process welding, etc.

PRODUCT PHOTOGRAPH





